



REV.	SPECIFICATION	ECN NO.	APPD.

**Material:**  
 Housing: PA9T, UL94V-0, Black.  
 Contacts: Brass.  
 Plating: Gold Plated on Contact Area and  $100\mu''$  Tin Plated on Solder Tail over Nickel  $50\mu''$ .

**Electrical Characteristics:**  
 Current Rating: 1.1 AMP.  
 Dielectric Withstanding Voltage: AC 500V for 1 minute.  
 Insulator Resistance:  $1000M\Omega$  min.  
 Contact Resistance:  $30m\Omega$  max.  
 Operating Temperature:  $-55^{\circ}C \sim +85^{\circ}C$ .

**Mechanical Characteristics:**  
 Insulation Force: 0.115 Kgf max Per. Contact Pair.  
 Withdrawal Force: 0.015 Kgf min Per. Contact Pair.

**\*RoHS Compliant**

8406-xx C 00 D U -P

- Series: 8406
- No. of Pin: xx
- Count: C
- Gold Plated: 00
- U: Tube Package
- D: SMD Type
- P: Plastic Pad
- Blank: W/O Pad
- T: Tape&Reel Package

Position	Dimension			
	A	B	C	D
36	7.65	6.00	25.00	9.15
64	21.65	20.00	39.00	23.15
98	38.65	37.00	56.00	40.15
164	71.65	70.00	89.00	73.15

<b>Tolerances</b>	Dwg. No.	8406D02002	<b>Title:</b>	
x = $\pm 0.50$	Projection		8406 Series	
.x = $\pm 0.25$	Unit	mm	Scale	1:1
.xx = $\pm 0.15$	Drawn By	Scott 06/27'16	PCI Express	
			SMD Type	

① 720

<b>OUPIN</b>			
OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 8406-xxC00DU-P			
SHEET	1/1	Ver.No.	A4